

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (Currently amended): A probe card structure comprising:

a probe section ~~sections comprising~~ having an insulated circuit board, ~~+~~ a probe ~~probes~~ of silicon material ~~which are being~~ formed on the said insulated circuit board, ~~and are in contact~~ for contacting with ~~the~~ a pad of a device to be measured, ~~+~~ and a conductive wiring ~~electrically connected in electrical~~ communication with ~~to the said probe probes~~ and ~~formed~~ disposed on the said insulated circuit board;

a supporting structure ~~structures which~~ for supporting ~~support each of the said probe section~~ sections;

a fixing structure ~~which~~ for ~~fixes~~ fixing ~~the~~ a plurality of said supporting structures together;

a printed circuit ~~which is~~ having a conductive wiring connected to ~~the~~ said fixing structure, said

printed circuit ~~and is being~~ electrically connected to ~~the~~ a measurement device for transmitting the a measurement signal ~~signals to the said device to be~~ being measured, ~~and has conductive wiring;~~ and

a wiring connection means for electrically connecting ~~the~~ said conductive wiring of ~~the~~ said probe ~~probes and the~~ said conductive wiring in communication with of ~~the~~ said printed circuit.

Claim 2 (Currently amending): The probe card structure ~~according to~~ of claim 1 ~~Claim 1~~, wherein ~~the~~ said supporting structures structure and ~~the~~ said fixing structure are made of ~~one~~ a material selected from the group consisting of invar, kovar, quartz, and ceramic, and any combinations thereof.

Claim 3 (Currently amended): The probe card structure ~~according to Claim 1~~ of claim 1, wherein ~~the~~ said conductive wiring of ~~the~~ said probe section and ~~the~~ said conductive wiring of ~~the~~ said printed circuit are electrically connected by a sub printed circuit, said sub printed circuit being selected from the group consisting of ~~which can be~~ a flexible printed circuit, a ~~or~~ rigid printed circuit board, and any combinations thereof.

Claim 4 (Currently amended): The probe card structure ~~according to of Claim 3,~~ claim 3, wherein ~~the~~ said conductive wiring of ~~the~~ said probe section and ~~the~~ a conductive wiring of ~~the~~ said sub printed circuit are electrically connected by a metallic wire, said metallic wire being formed by ~~the~~ a wire bonding method.

Claim 5 (Currently amended): The probe card structure ~~according to Claim 3,~~ of claim 3, wherein ~~the~~ said conductive wiring of ~~the~~ said probe section and ~~the~~ a conductive wiring of ~~the~~ a flexible circuit are electrically connected by ~~the~~ an anisotropic conducting film.

Claim 6 (Currently amended): The probe card structure ~~according to Claim 3,~~ of claim 3, ~~wherein~~ further comprising at least one capacitor ~~is installed~~ to reduce ~~the~~ an electric noise on ~~the~~ a flexible printed circuit.

Claim 7 (Currently amended): The probe card structure ~~according to Claim 3,~~ of claim 3, ~~wherein~~ further comprising a contact pad of ~~the~~ said sub printed circuit and ~~the~~ a contact pad of ~~the~~ said insulated circuit board ~~are~~ electrically connected by a pogo pin.

Claim 8 (Currently amended): The probe card structure ~~according to Claim 3~~ of claim 3, wherein further comprising the a contact pad of the said sub printed circuit and the a contact pad of the said insulated circuit board are electrically connected by an perpendicular conductor of silicon rubber material which conducts for conducting electricity between a top and a bottom surface through a plurality of vertically embedded metallic wires with having a diameter of 35µm or less, said plurality of vertically embedded metallic wires being positioned in an array of a 0.07 [~] through 0.45mm matrix.

Claim 9 (Currently amended): The probe card structure ~~according to Claim 3~~ of claim 3, wherein further comprising a plating layer is formed on the said probe of the said probe section and the said conductive wiring of said probe section.

Claim 10 (Currently amended): The probe card structure ~~according to Claim 9~~ of claim 9, wherein the said plating layer is formed by selected from the group consisting of a nickel plating layer, or a gold plating layer, and any combinations thereof.

Claim 11 (Currently amended): The probe card structure ~~according to Claim 10~~ of claim 10, wherein further comprising a groove is formed at the a tip of

~~the said probe probes~~ before the said plating layer is formed.

Claim 12 (Currently amended): The probe card structure ~~according to Claim 1, of claim 1, wherein~~ further comprising at least a screw ~~is~~ installed in the said supporting structure ~~to for adjust~~ adjusting the ~~3-dimensional a locations~~ location of the said supporting ~~structures~~ structure and the said fixing ~~structures~~ structure, said location being adjustable in three dimensions.

Claim 13 (Currently amended): The probe card structure ~~according to Claim 1, of claim 1, wherein~~ further comprising at least a screw ~~is~~ installed in the said fixing structure, said screw to for adjusting ~~adjust the 3-dimensional a location~~ locations of the said supporting ~~structures~~ structure and the said fixing ~~structures~~ structure, said location being adjustable in three dimensions.